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IN THE SPECIFICATION:

Page 3, please replace the paragraph beginning on line 21 with the following paragraph:

In a soldering tank, soldering of a large number of printed circuit boards is carried out, so the solder alloy in the solder bath adheres to the printed circuit board and decreases in amount. In the past, supply of the amount by which the solder decreased was carried out using a solder alloy not containing P. Namely, the decrease in the P concentration and the decrease in the solder alloy were separately controlled. As a result, a small amount of a solder alloy having a high concentration of P was charged into the solder bath as the P in the solder in the solder bath decreased, and a solder alloy not containing any P was supplied as the solder in the solder bath decreased.

Page 21, line 3, please delete the entire paragraph beginning with the words "Soldering Method".

Page 21, line 5, please delete the entire paragraph beginning with the words "In this invention".

Page 21, line 9, please delete the entire paragraph beginning with the words "As a simple method".

Page 21, after line 13 (after the deleted paragraphs),
please insert the following new paragraph:

The rate of decrease of an oxidation suppressing element in a solder bath is measured during a soldering operation. Soldering is then carried out while replenishing the solder bath is then replenished during soldering so as to maintain the surface level of molten solder in the bath with a replenishment solder alloy which supplies the oxidation suppressing element to the solder bath at at least the rate at which the oxidation suppressing element is consumed during soldering. When the oxidation suppressing element is P, the concentration of P in the replenishment solder alloy is preferably 60 - 100 ppm.